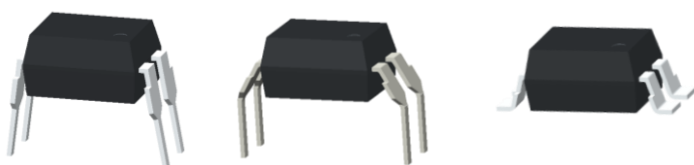
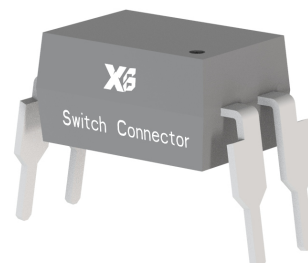
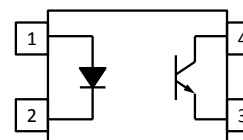


### 4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL817H-G Series



Schematic



#### Features:

- Halogens free.  
(Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)
- Current transfer ratio  
(CTR: 50~400% at  $I_F = 5\text{mA}$ ,  $V_{CE} = 5\text{V}$ )
- Operating temperature  $-55^{\circ}\text{C} \sim 125^{\circ}\text{C}$
- High isolation voltage between input and output (Viso = 5000Vrms)
- Creepage distance > 7.62mm
- Compact small outline package
- Compliance with EU REACH.
- The product itself will remain within RoHS compliant version
- UL and cUL approved(No.E214129)
- VDE approved (No.132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

#### Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

#### Description

The EL817H-G series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector. They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

#### Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

### Absolute Maximum Ratings (Ta=25°C)\*1

	Parameter	Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	50	mA
	Peak forward current (1us, pulse)	I <sub>FP</sub>	1	A
	Reverse voltage	V <sub>R</sub>	6	V
	Power dissipation	P <sub>D</sub>	100	mW
Output	Power dissipation	P <sub>C</sub>	150	mW
	Collector current	I <sub>C</sub>	50	mA
	Collector-Emitter voltage	V <sub>CEO</sub>	80	V
	Emitter-Collector voltage	V <sub>ECO</sub>	7	V
Total Power Dissipation		P <sub>TOT</sub>	200	mW
Isolation Voltage*2		V <sub>ISO</sub>	5000	V rms
Operating Temperature		T <sub>OPR</sub>	-55 to 125	°C
Storage Temperature		T <sub>STG</sub>	-55 to 150	°C
Soldering Temperature*3		T <sub>SOL</sub>	260	°C

Notes:

\*1 Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

\*2 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

\*3 For 10 seconds

## Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

### Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	$V_F$	-	1.2	1.4	V	$I_F = 10\text{mA}$
Reverse Current	$I_R$	-	-	10	$\mu\text{A}$	$V_R = 5\text{V}$
Input capacitance	$C_{in}$	-	30	250	pF	$V = 0, f = 1\text{kHz}$

### Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	$I_{CEO}$	-	-	200	nA	$V_{CE} = 48\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	$BV_{CEO}$	80	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	$BV_{ECO}$	7	-	-	V	$I_E = 0.1\text{mA}$

### Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL817H	50	-	400	%	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$
	EL817HA	80	-	160		
	EL817HB	130	-	260		
	EL817HC	200	-	400		
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-	-	0.35	V	$I_F = 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	$R_{IO}$	$5 \times 10^{10}$	-	-	$\Omega$	$V_{IO} = 500\text{Vdc}, 40 \sim 60\% \text{ R.H.}$
Floating capacitance	$C_{IO}$	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Cut-off frequency	$f_c$	-	80	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}$ $R_L = 100\Omega, -3\text{dB}$
Rise time	$t_r$	-	6	18	$\mu\text{s}$	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$
Fall time	$t_f$	-	8	18	$\mu\text{s}$	

\* Typical values at  $T_a = 25^\circ\text{C}$

## Typical Electro-Optical Characteristics Curves\*

Figure 1. Forward Current vs Forward Voltage

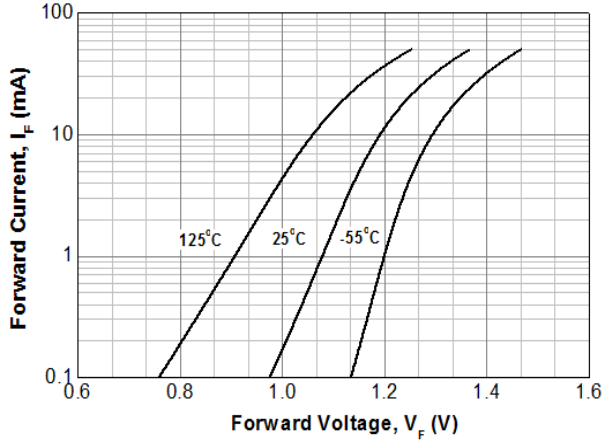


Figure 2. Normalized Current Transfer Ratio vs Forward Current

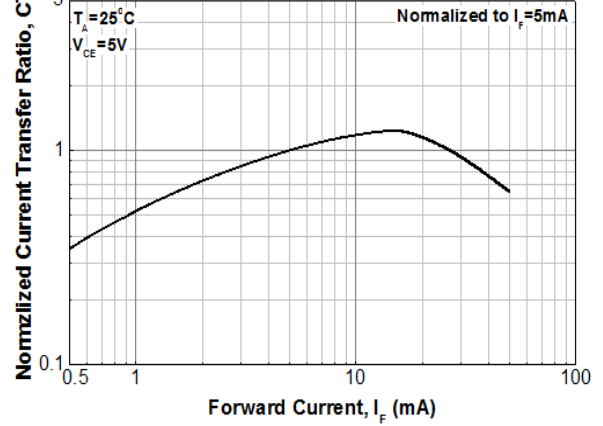


Figure 3. Current Transfer Ratio vs Ambient Temperature

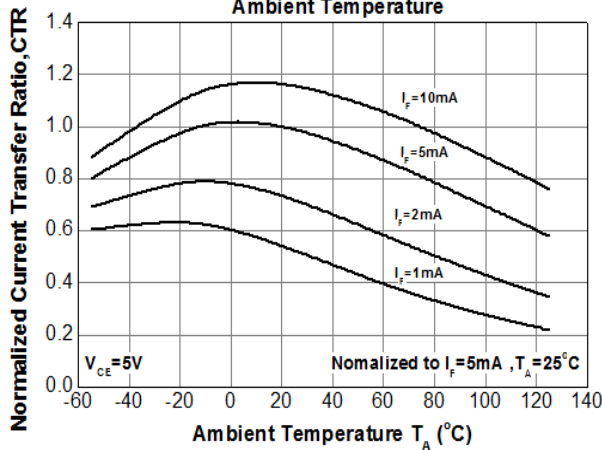


Figure 4. Dark Current vs Ambient Temperature

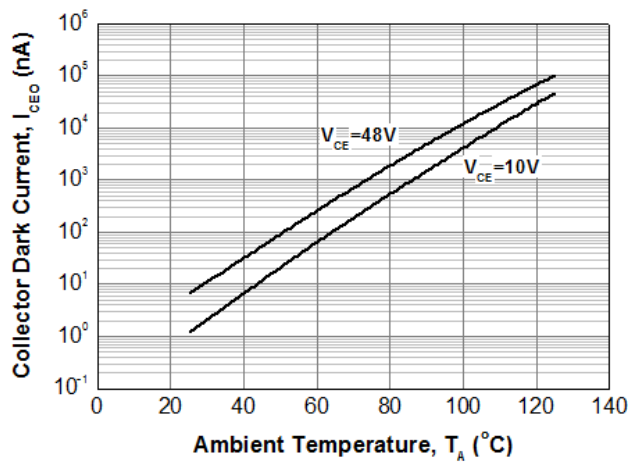


Figure 5. Collector-Emitter Saturation Voltage vs Collector Current

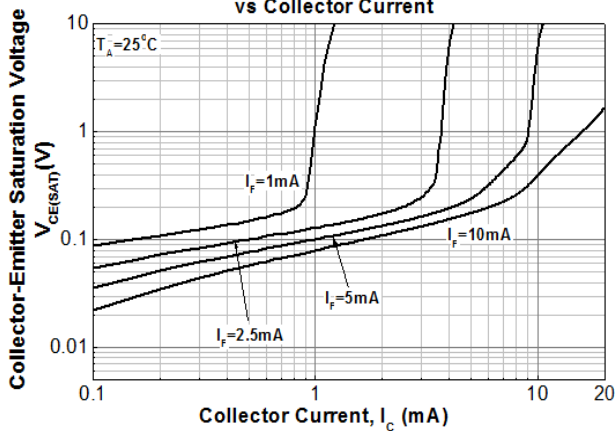
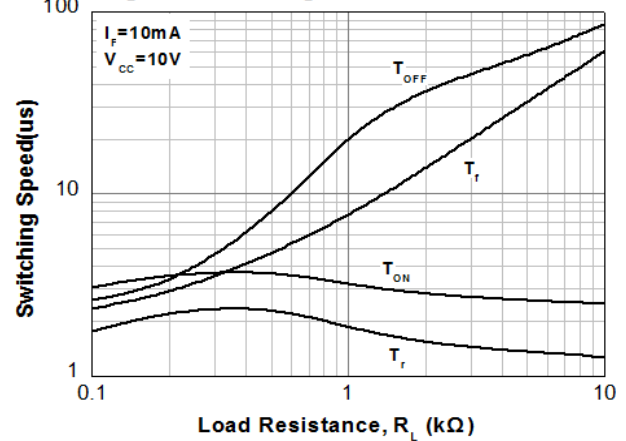


Figure 6. Switching Time vs Load Resistance



\*Please be aware that all data in the graph are just for reference and not for guarantee.

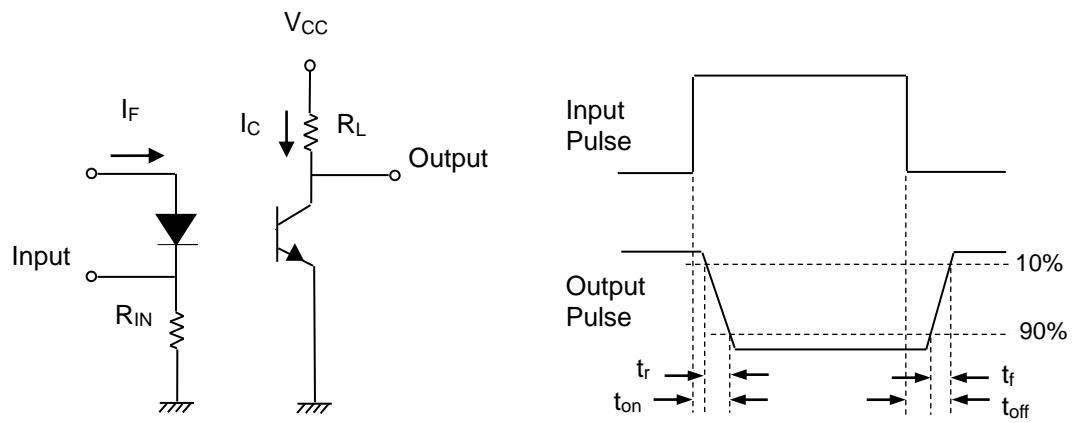


Figure 7. Switching Time Test Circuit & Waveforms

## Order Information

### Part Number

**EL817HX(Y)(Z)-VG**

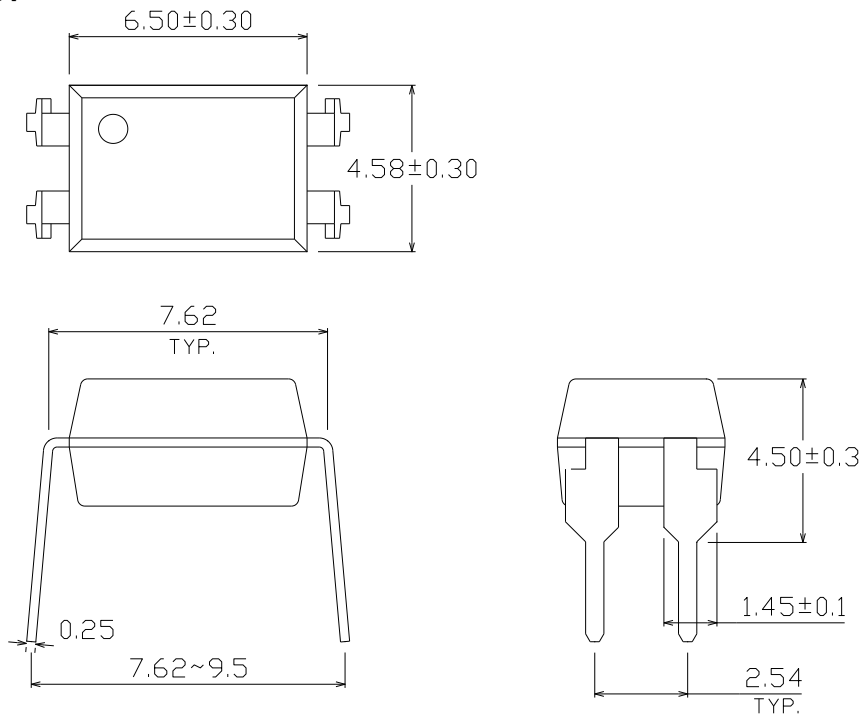
### Note

H = Operating high temperature  
X = Lead form option (S1, S2, M or none)  
Y = CTR Rank (A, B, C or none)  
Z = Tape and reel option (TU, TD or none)  
V = VDE safety (optional)  
G = Halogens free

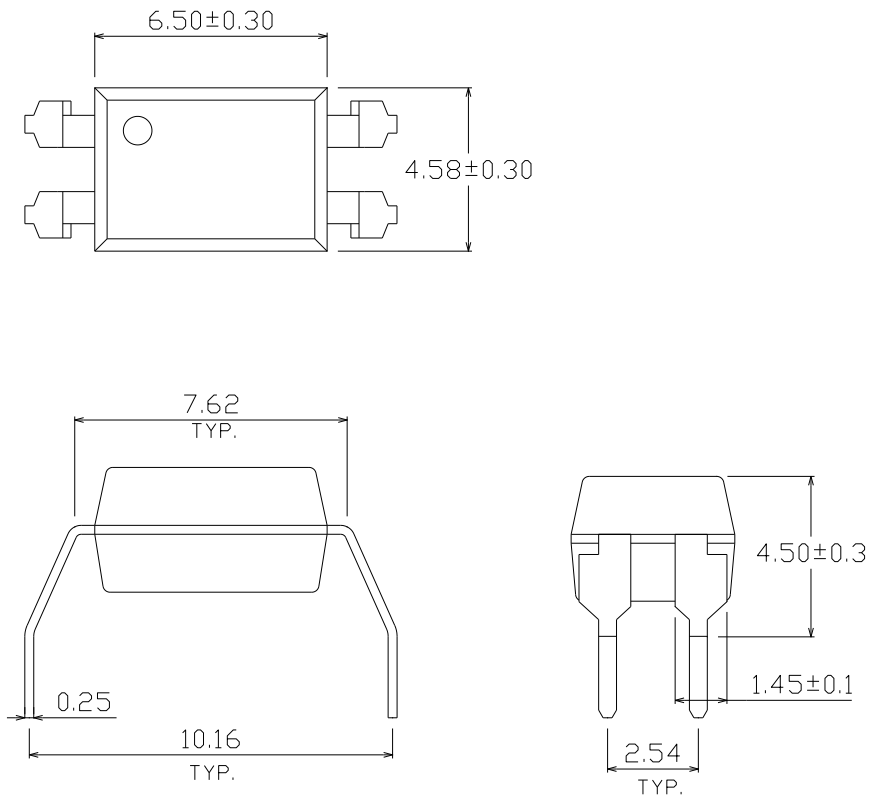
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel
S2 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S2 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

Package Dimension (Dimensions in mm)

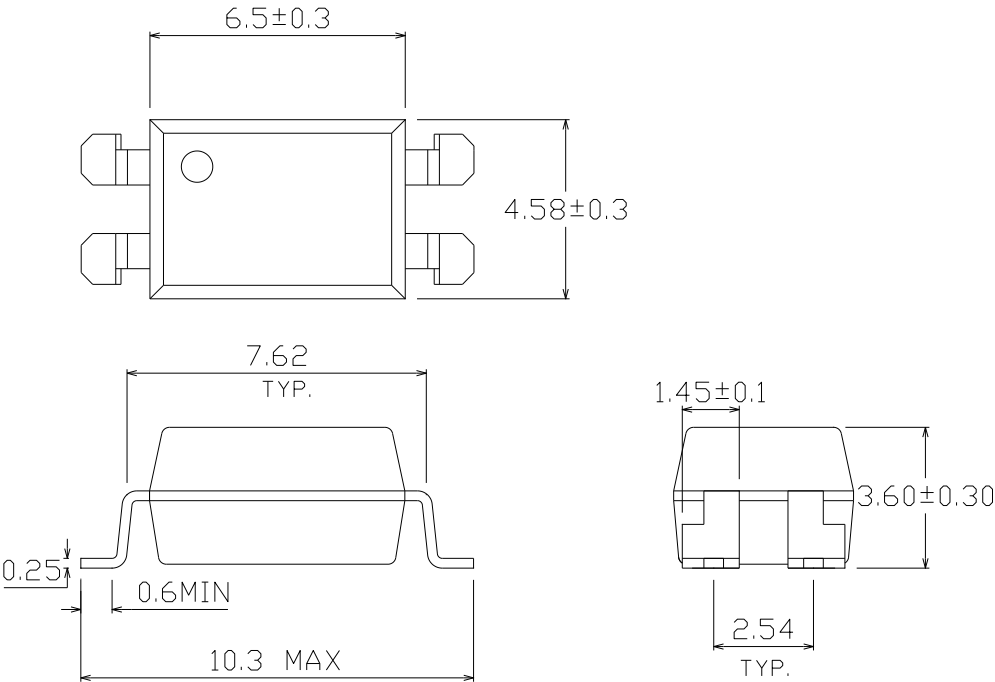
Standard DIP Type



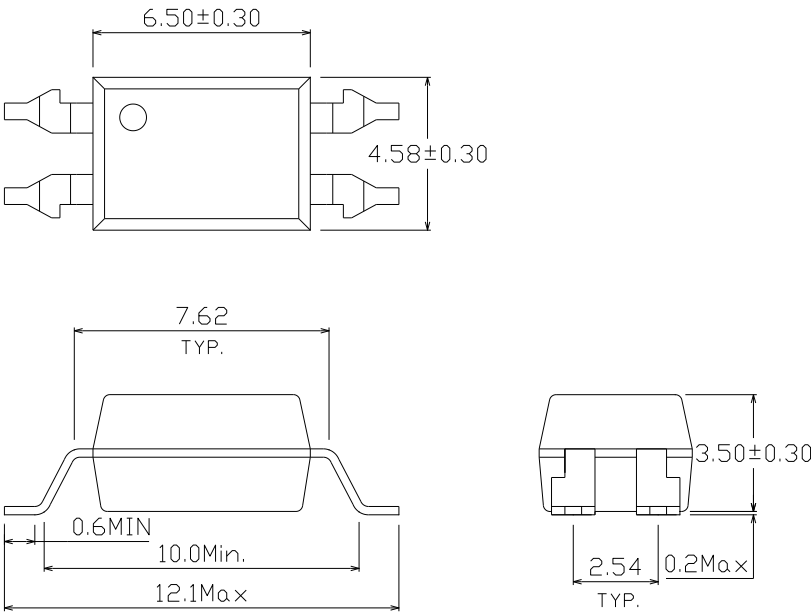
Option M Type



Option S1 Type

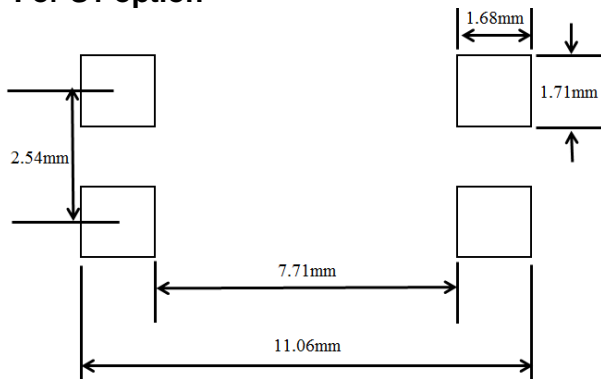


Option S2 Type

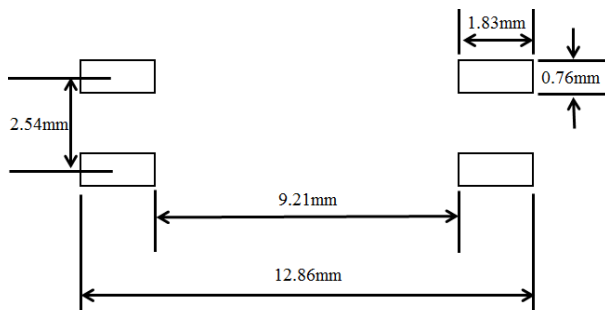


## Recommended pad layout for surface mount leadform

### For S1 option



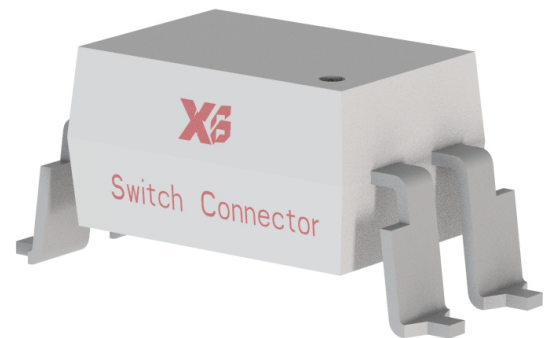
### For S2 option



### Notes

Suggested pad dimension is just for reference only.  
Please modify the pad dimension based on individual need.

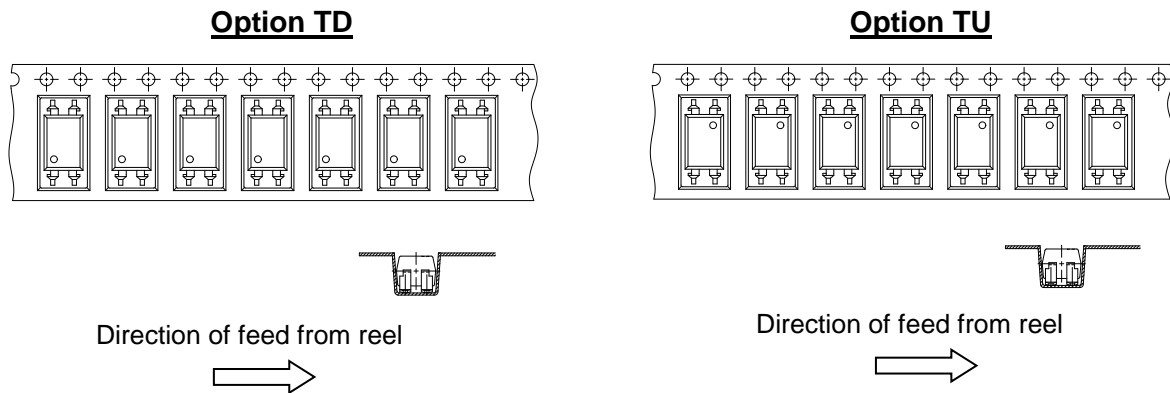
## Device Marking



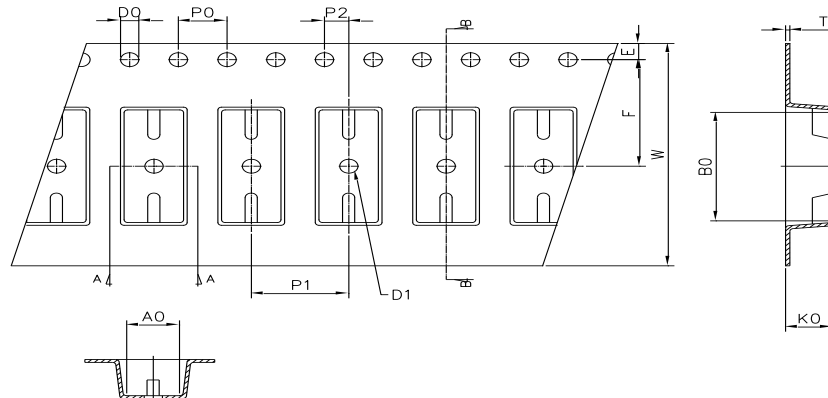
### Notes

EL denotes XI BNANG  
817 denotes Device Number  
H denotes Operating High Temperature  
F denotes Factory Code (G: China and Green part)  
R denotes CTR Rank (A, B, C or none)  
Y denotes 1 digit Year code WW  
denotes 2 digit Week code V  
denotes VDE (optional)

## Tape & Reel Packing Specifications



## Tape dimensions

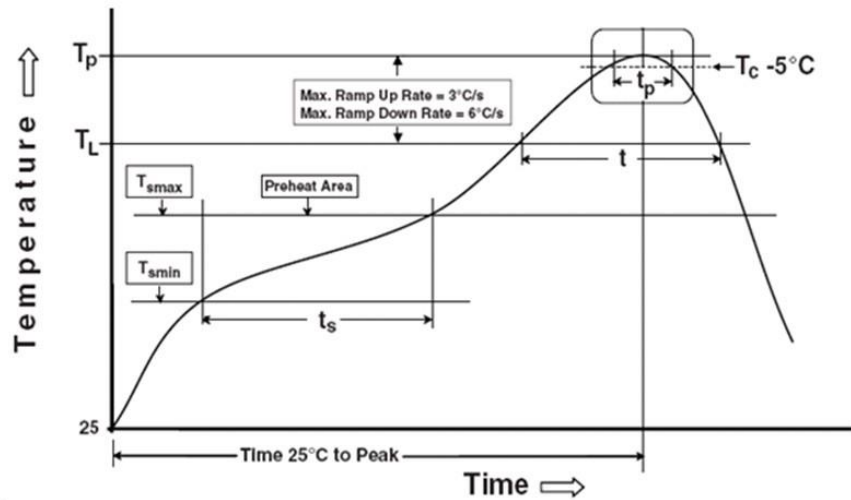


Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S2	4.88±0.1	12.55±0.1	1.5±0.1	1.50±0.1	1.75±0.1	11.5±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1
Dimension (mm) S2	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	24.00±0.3	4.00±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. XI BNANG assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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